

A Single Chip Shared Memory Switch with Twelve 10Gb Ethernet Ports

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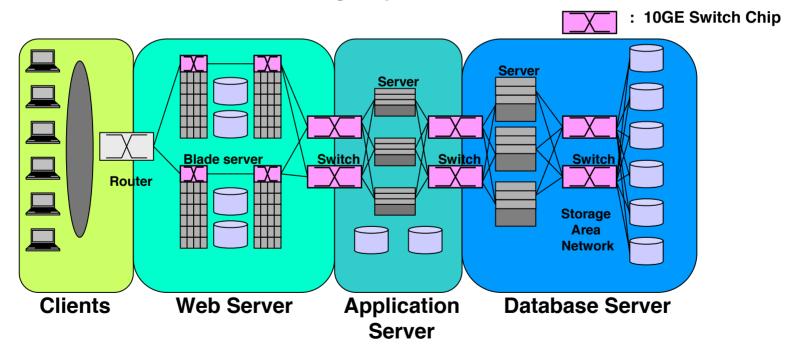
Outline

- Background
- Overview and Features
- Switch Implementation
- Evaluation
- Summary



Background

- IP-based networks connect all the computing resources (All-IP).
- Ethernet protocol is commonly used for IP networks.
- 10Gb Ethernet is a promising solution for unified, fat pipe between servers and storage systems.





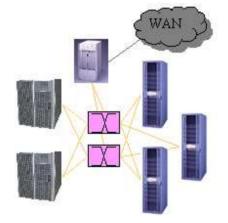
Primary Target Applications

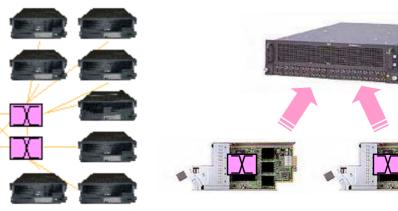
- Our primary target is infrastructure for computing platform, such as SAN, Clusters, Blade Servers.
- Those applications require short latency, low cost and high density.
 - Motivation to develop a dense 10Gb Ethernet switch.
- So, the design strategy is set as follows.
 - Focus on layer-2 switching.
 - High-throughput/low latency switch core.
 - SerDes integration for copper solution.

Storage Area Network

Cluster Computing

Blade Server

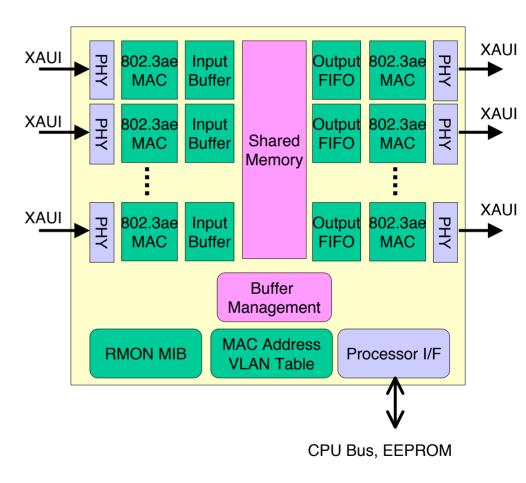






MB87Q3050 Overview

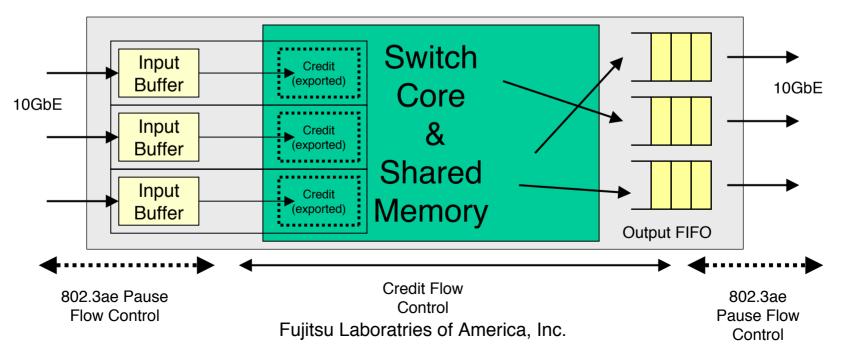
- Twelve 10 Gb Ethernet ports.
- Integrated SerDes for XAUI.
 - 3.125Gbps x 4 lane/direction
- Layer-2 switching with 802.1Q VLAN.
- Output queue switching using shared memory.
- 240 Gbps shared memory bandwidth.
- Cut-through forwarding.
- Statistics counters for RMON.





Designing a Switch Core

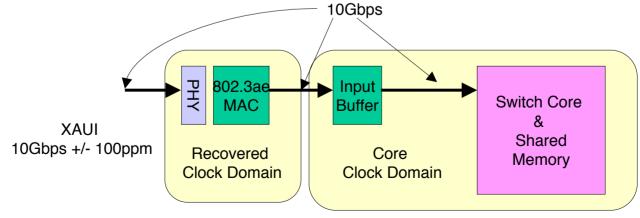
- A protocol independent switch core was developed.
 - Credit based flow control.
 - Packet by packet operation, allowing variable length from 64B to 9KB.
 - This is not a fixed-length cell switch.
 - Four level priority queue, with simple distributed arbiters per output port.
 - Cut-through forwarding (fall-through latency of the core: 150ns)
 - Multicast support for "single copy, multiple read".





Input Buffering for Cut-Through

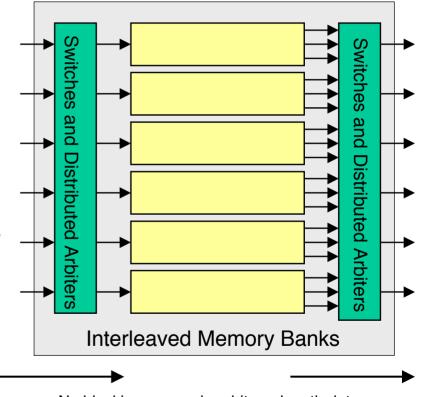
- The switch core is designed for cut-through forwarding of variable length frames.
 - The switch core has NO speed-up in terms of the bandwidth per port.
 - All the data path in the switch isrunning at 10Gbps data rate.
 - Popular implementation with crossbar switches may have increased B/W per port.
 - The switch core assumes NO fragmentation.
 - The entire packetshould be transferred at 10Gbps rate.
 - These features are desired to handle variable length frames in Ethernet protocol, to minimize store&forward operation.
- Input buffering is simply for speed-matching between clock domains when cut-through mode is chosen.





On-chip Interconnect for Shared Memory

- An on-chip memory sub-system is designed for 12 10Gbps reads AND 12 10Gbps writes.
 - "Multi-port Stream Memory"
- Deep interleaved memory banks are connected via distributed, multi-stage interconnection network.
 - "No global arbitration" is a good policy for chip integration and timing closure.
- Switching is rescheduled at every packet boundary for access path arbitration.
- Arbitration delay exists between packets (as shown later).

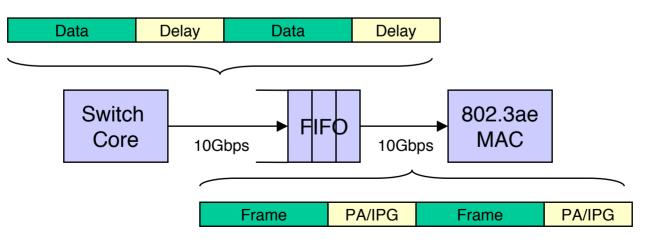


No blocking access in arbitrary length data Arbitration delay between data streams



Output Buffering for Short Latency

- Frames come out of the switch core without fragmentation, at 10Gbps rate.
- However, arbitration delay (caused by theon-chip interconnect) exists between frames.
- The average value is 32 cycle (assuming random, full-loaded traffics).
- On the other hand, outgoing packets has 8 byte preamble and 12 byte IPG as defined in the Ethernet protocol.
 - 5 cycles between frames in the switch core.
- Thus, with a small amount of FIFO, it is possible to sustain wire-speed throughput.
 - We do not need a large FIFO. The size is much smaller than the maximum packet size.
 - It also helps to reduce the fall-through latency in a loaded condition.

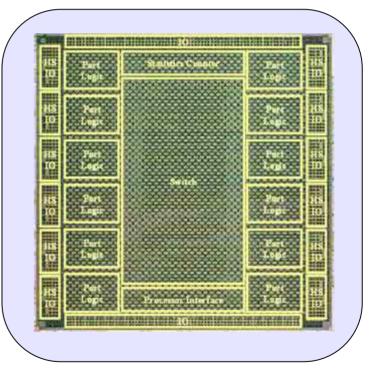




Chip Implementation

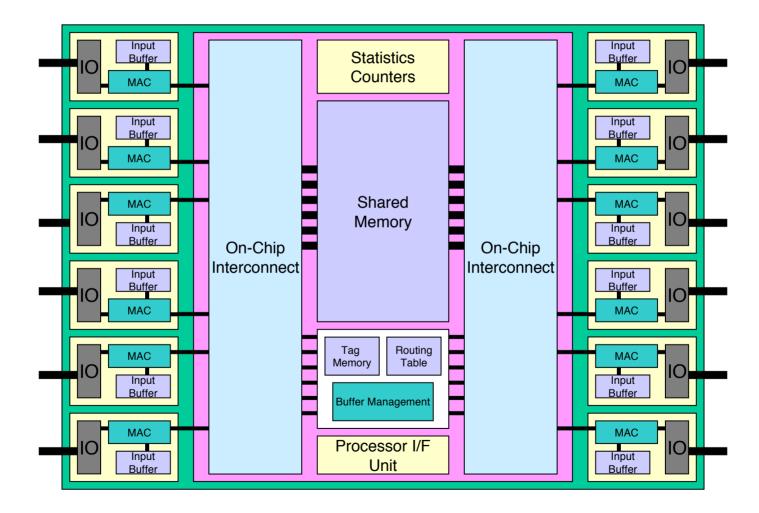
Items	Specification	
Technology	Fujitsu CS91: 0.11um CMOS ASIC	
Logic	6.3M gates (total)	
SRAM	897K Bytes (total)	
Core Logic Frequency	312.5MHz	
Package	FCBGA-728	
Signals	336	
High Speed IO	XAUI (3.125Gb/s x 4) X 12	
Power Consumption	15.3 W (typical), full-loaded	
Die Size	16mm x 16mm	

MB87Q3050 12-port, 10Gbps Ethernet Switch Chip





Floorplan Image

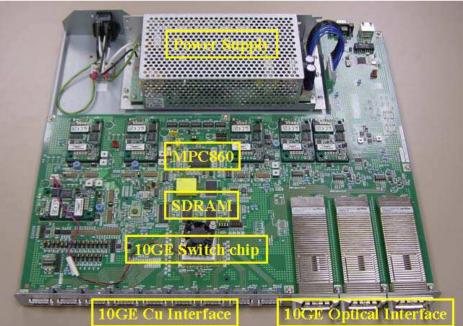




Evaluation Board

- For functional validation
 - Hardware
 - Firmware
- Nine copper cable connectors.
 - Tested with copper cables up to 5m.
- Three optical Interfaces.
 - XENPAK modules.

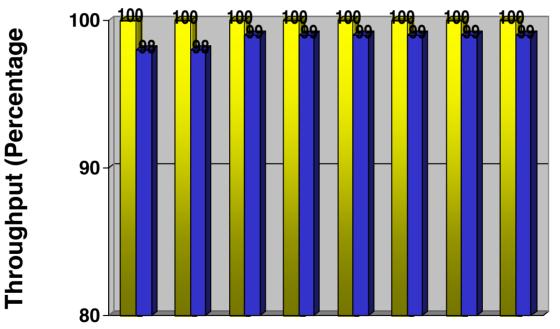
Evaluation Board Top View





Performance: Zero-loss Throughput

- Zero-loss Throughput is measured using the *first-silicon*.
 - Optical links are used for 2-port paring configuration.
 - Optical links and Cupper cables are used for full mesh configuration.
 - Slight packet loss is observed(to be fixed in future silicon).





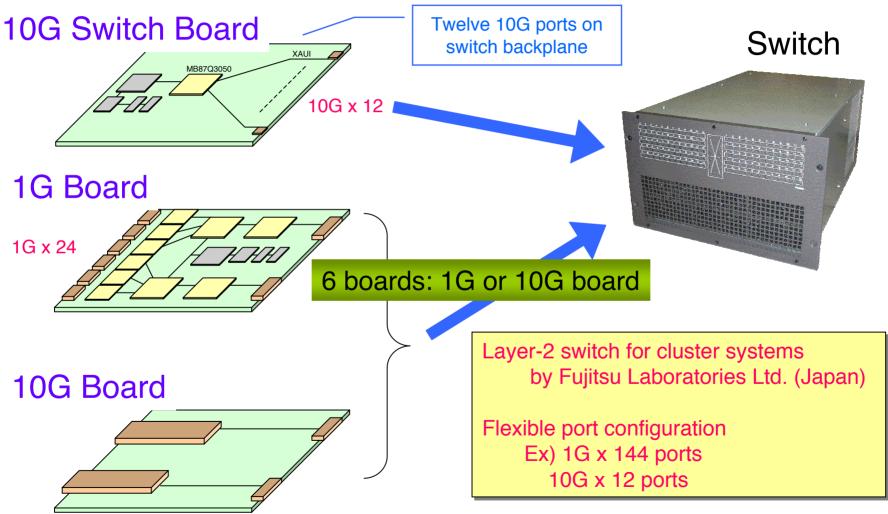
Performance: Latency

• Fall-through latency at 100% throughput workload is measured with the first silicon.

	Latency(nsec)	
Packet size bytes	Cupper Cable	Optical Cable (w/ XENPAK modules)
64	750	1160
128	670	1090
256	660	1190
512	630	1230
1024	670	1280
1280	640	1140
1518	630	1190
9216	660	1220



Application Prototype:1Gb Switch Box





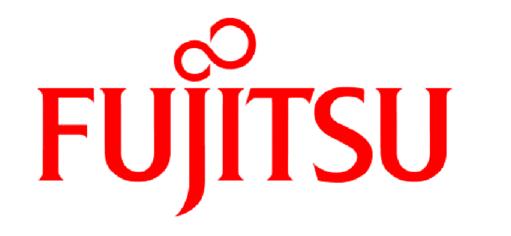
Summary

- MB87Q3050 was designed for 10Gb Ethernet-based interconnection for servers and storage equipment.
 - Low cost, dense integration.
 - high-throughput, low latency.
- The switch achieves wire-speed operation at each port, by 240Gbps shared memory bandwidth.
- It also achieves 450ns latency with cut-through forwarding.

Acknowledgement:

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THE POSSIBILITIES ARE INFINITE